# UNR911TJ (UN911TJ)

### Silicon PNP epitaxial planer type

For digital circuit

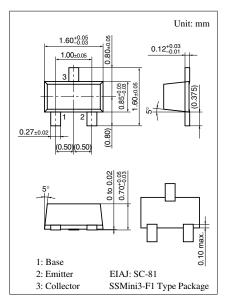
For switching

### Features

- Costs can be reduced through downsizing of the equipment and reduction of the number of parts.
- SS-mini type package, allowing automatic insertion through tape packing.
- Flat lead type, high mounting efficiency

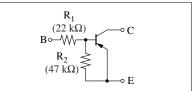
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Parameter	Symbol	Rating	Unit
Collector to base voltage	V <sub>CBO</sub>	-50	V
Collector to emitter voltage	V <sub>CEO</sub>	-50	V
Collector current	I <sub>C</sub>	-100	mA
Total power dissipation	P <sub>T</sub>	125	mW
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

### Absolute Maximum Ratings $T_a = 25^{\circ}C$



#### Marking Symbol: EY

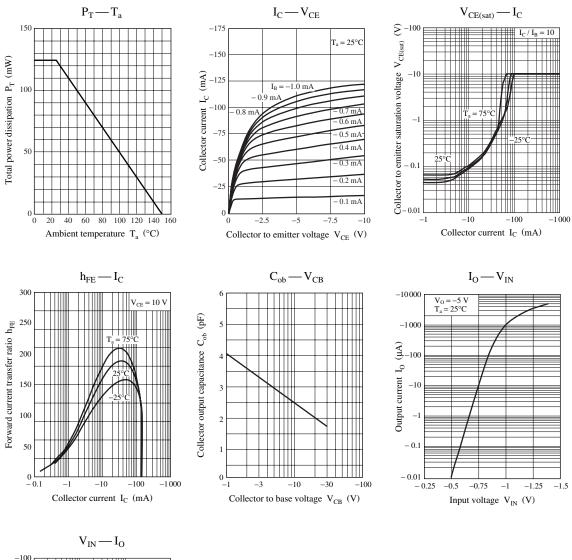
#### Internal Connection

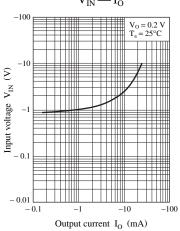


#### Parameter Symbol Conditions Min Max Unit Тур $V_{CB} = -50 \text{ V}, I_E = 0$ Collector cutoff current I<sub>CBO</sub> -0.1μΑ $V_{CE} = -50 \text{ V}, I_B = 0$ - 0.5 I<sub>CEO</sub> μΑ $V_{EB} = -6 V, I_C = 0$ Emitter cutoff current -0.2 $I_{EBO}$ mA Collector to base voltage V<sub>CBO</sub> $I_C = -10 \ \mu A, I_E = 0$ -50V $I_{C} = -2 \text{ mA}, I_{B} = 0$ -50v Collector to emitter voltage V<sub>CEO</sub> $V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$ Forward current transfer ratio h<sub>FE</sub> 80 400 $I_{C} = -10 \text{ mA}, I_{B} = -0.3 \text{ mA}$ - 0.25 V Collector to emitter saturation voltage V<sub>CE(sat)</sub> High-level output voltage V<sub>OH</sub> $V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$ -4.9 V $V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$ Low-level output voltage VOL -0.2V Input resistance -30% +30% kΩ $R_1$ 22 Resistance ratio $R_1/R_2$ 0.47 Transition frequency $f_T$ $V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$ 80 MHz

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) The part number in the parenthesis shows conventional part number.





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